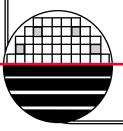
ROCHESTER INSTITUTE OF TECHNOLOGY MICROELECTRONIC ENGINEERING

# **Bruce Furnace Recipes**

## **Dr. Lynn Fuller**

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7-5-2014 Bruce\_Furnace.ppt

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## **OUTLINE**

**Bruce Furnace Bruce Furnace Recipes Advanced Recipes** Calculations List of Recipes **Recipe Details** Measurement of Oxide Thickness Recall of Run Data Stabilization After Push Non Uniform Oxide Growth Problems SPC Out of Control Action Plans Bake of Spin-on Dopants Creating New Recipes References

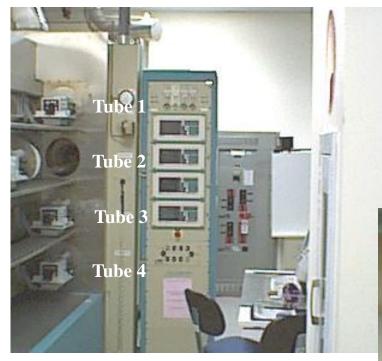
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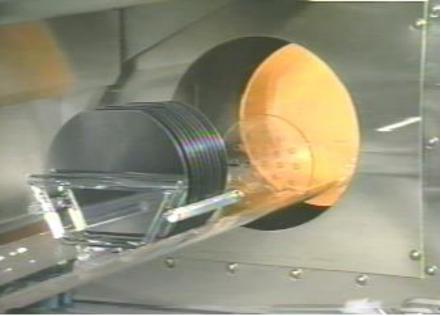


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#### **BRUCE FURNACE**

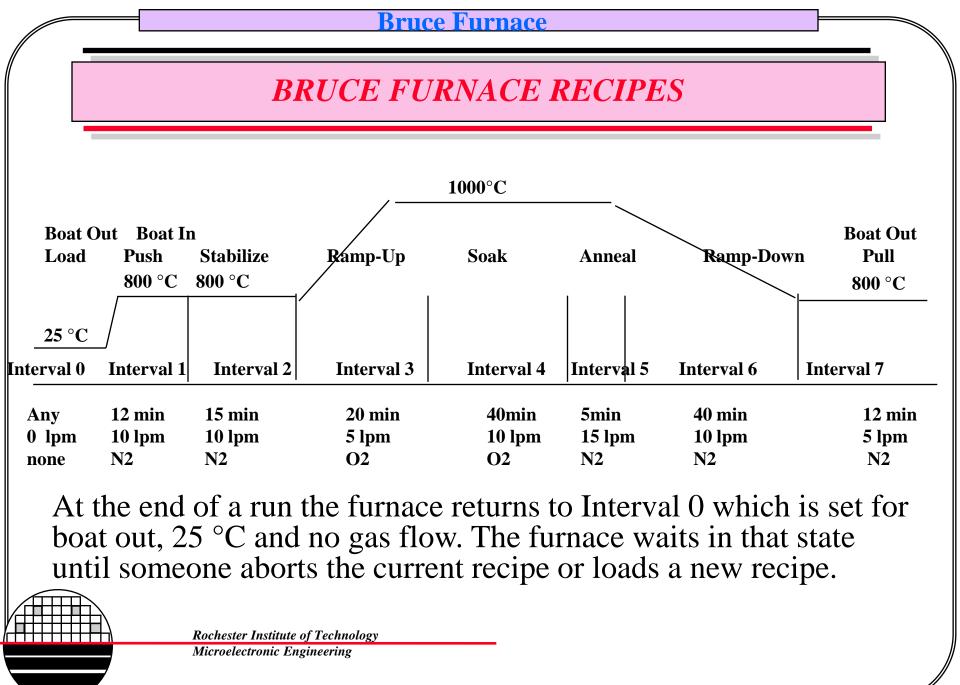


Tube 1 Steam Oxides Tube 2 P-type Diffusion Tube 3 N-type Diffusion Tube 4 Dry Oxides and Gate Oxides

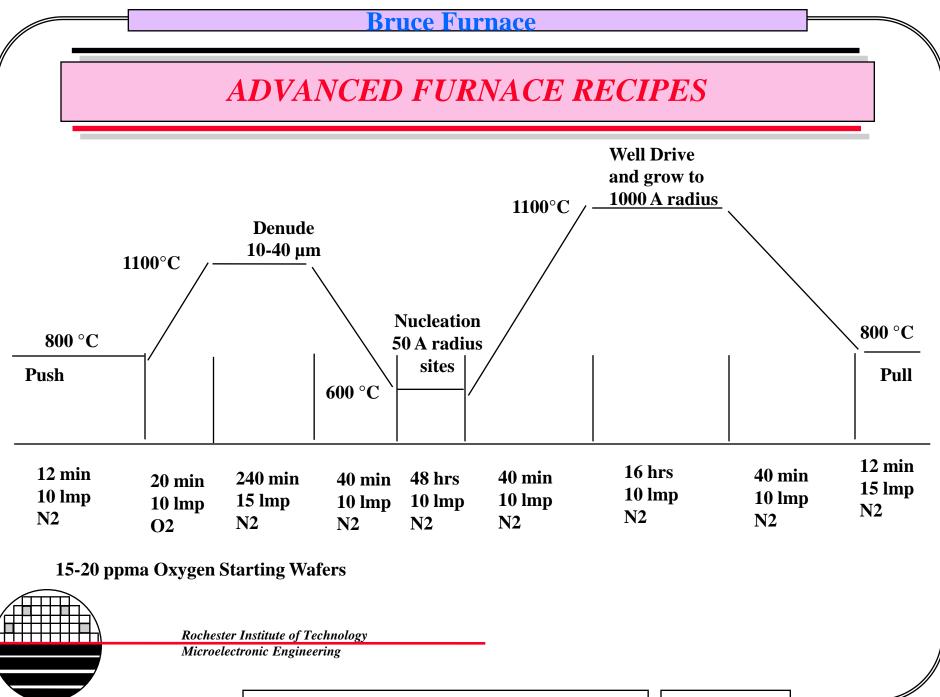




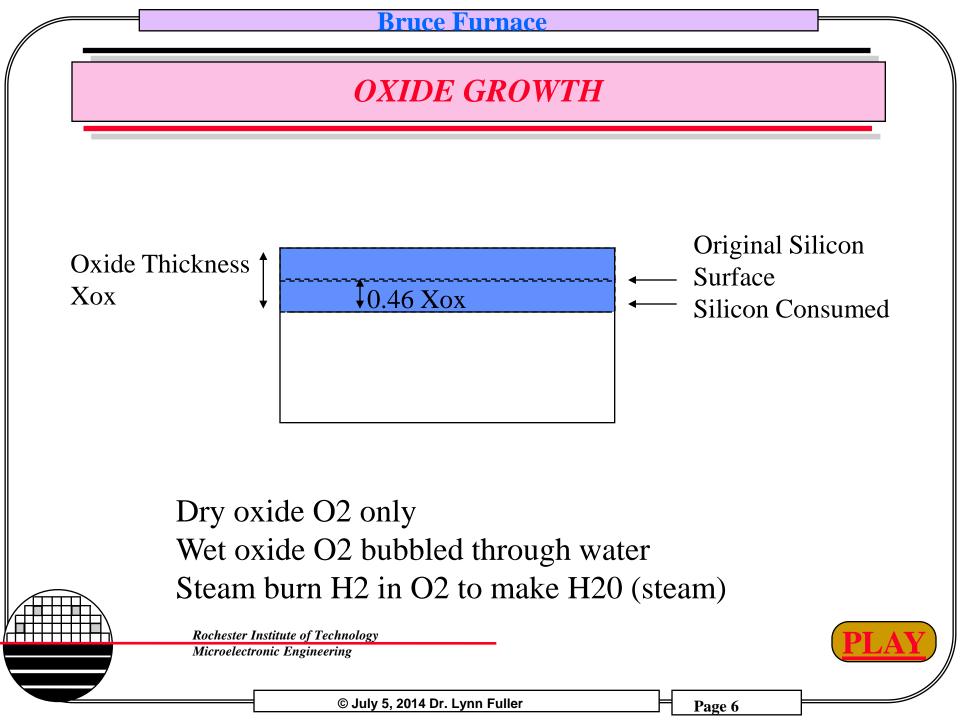
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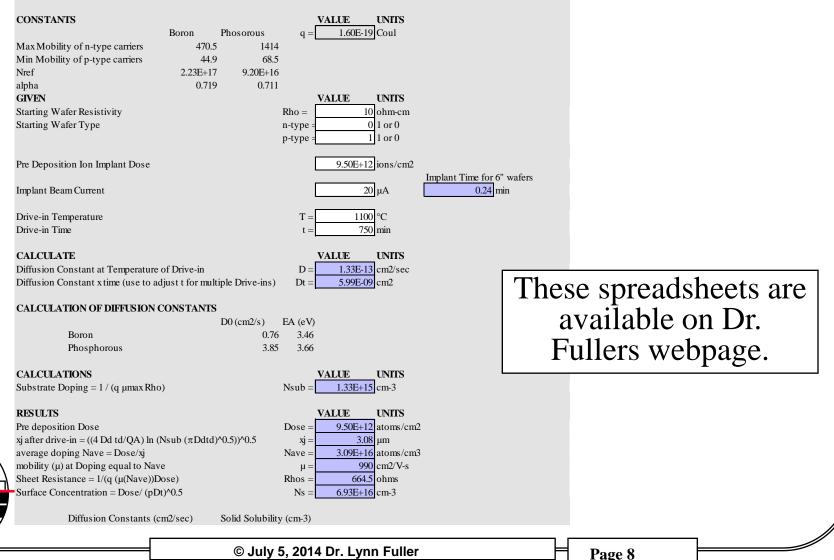


### USING EXCEL SPREADSHEET FOR OXIDE GROWTH CALCULATIONS

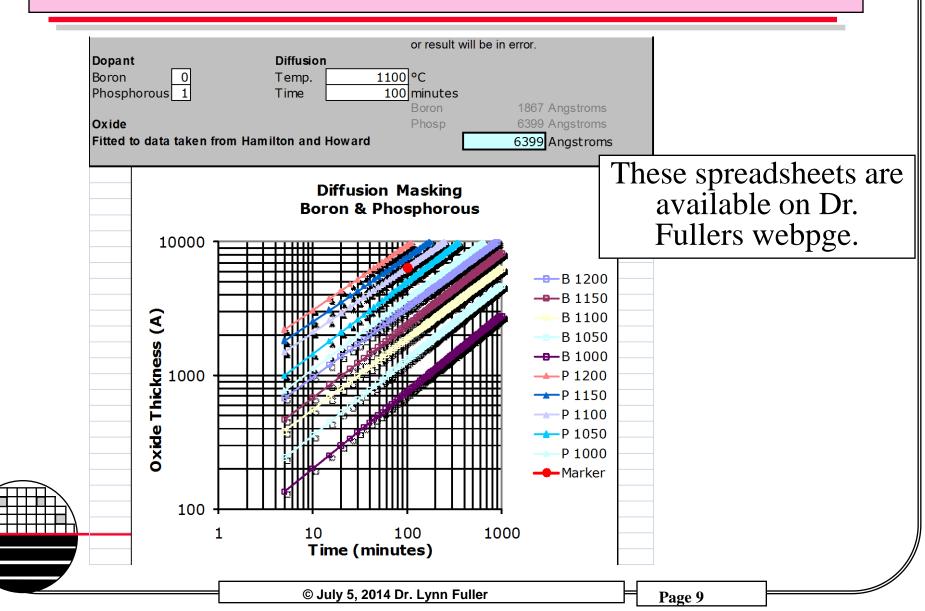
		A E	B   C	C D	E	F G	Н	I J	Γ			
		ROCHESTER INST			Y		OXIDE					
		MICROELECTRONIC ENGINEERING 7/4/2014										
	3											
		CALCULATION OF OXIDE THICKNESS Dr. Lynn Fuller / Jamie Wasiewicz										
	5	To use this spreadsheed change the values in the white boxes. The rest of the sheet is										
		protected and should										
		alculated results are										
		ourning H2 with O2	is called "s	steam"	$  Th_{\Theta}$	ese spreads	hoote aro					
	0									se spreaus	sincers are	
		CONSTANTS			VARIABLES			CHOICES		<b>▲</b>		
	2 k		3E-23 J/K					1=yes, 0=no	-	available (	)n Dr.	
			30000 µm/h	ar	Temp =	900 °C	wet					
		Ea (dry)	2 eV		time =	42 min	dry		-	Fullers we	nnage	
		Bo/Ao) wet 8950		hr Partial Pres	ssure, p =	1.00 Atm	steam	1		uners we	opage.	
		Ea (wet)	2.05 eV				<100>	1				
		Bo/Ao) stean 1.63		hr			<111>		-			
		Ea (steam)	2.05 eV	_					-			
		~	E+02 µm2/	/hr	Xint=	ΑÔ			-			
		Ea (dry)	1.23 eV	_					-			
			E+02 µm2/	/hr	Silicon VLSI Te				-			
		Ea (wet)	0.71 eV	_	Prent	tice Hall, 2000	), pg 319-36	9	-			
			E+02 µm2/						-			
		Ea (steam)	0.78 eV		(Bo/Ao)/1.68 fo	or <100>						
	25											
		CALCULATIONS:										
	27											
	28		Xox (Oxide	thickness)=(A/2)	([1+(t+Tau)4E	WA^2]^0.5-1	} =1	005 Å				
	29		_ /_									
	30			a/KTemp)]*p		37431 µm2/h						
	B/A = [(Bo/Ao) exp (-Ea/KTemp)]*p $1.57E-01 \mu m/hr$											
	32	A			1.11	00164 µm						
	33	Tau =	= (Xi2+AXi	1)/B		0 hr						
	34											
$\mathbf{L}$	35	Vau 🛉 🗖		Oxide-Si	102		. 🕴 .					
╀┼╲╶┊	36 37	Xox I			PQ-2			rigional Silicon				
╤┲┛╢╞	37	S	ilicon					urface Prior to xide Growth				
			moon				1 0	AIGE GIOWIN				
	39 40						0.46 Xox (s	silicon consumed)				
	+0 41											
	10											
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### USING EXCEL SPREADSHEET FOR D/S JUNCTION DEPTH & SHEET RHO CALCULATIONS

#### CALCULATION OF ION IMPLANT JUNCTION DEPTH AND SHEET RESISTANCE AFTER DRIVE-IN



### MINIMUM OXIDE NEEDED TO MASK DIFFUSION



### **OXIDE THICKNESS COLOR CHART**

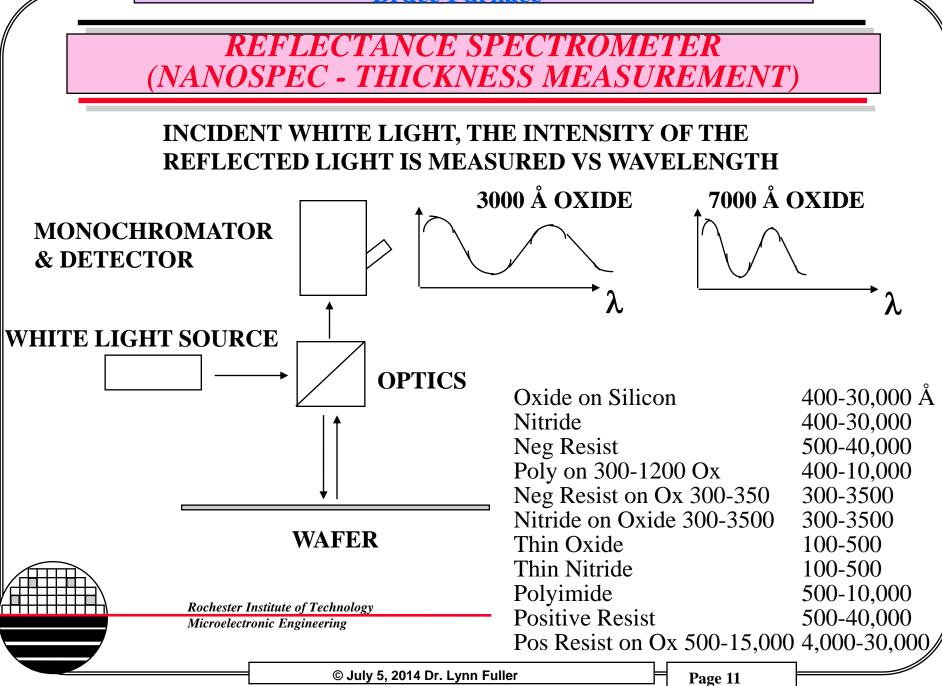
Thickness	Color
500	Tan
700	Brown
1000	Dark Violet - Red Violet
1200	Royal Blue Blue
1500	Light Blue - Metallic Blue
1700	Metallic - very light Yellow Green
2000	Light Gold or Yellow - Slightly Metallic
2200	Gold with slight Yellow Orange
2500	Orange - Melon
2700	Red Violet
3000	Blue - Violet Blue
3100	Blue Blue
3200	Blue - Blue Green
3400	Light Green
3500	Green - Yellow Green
3600	Yellow Green
3700	Yellow
3900	Light Orange
4100	Carnation Pink
4200	Violet Red
4400	Red Violet
4600	Violet
4700	Blue Violet

Thickness	Color
4900	Blue Blue
5000	Blue Green
5200	Green
5400	Yellow Green
5600	GreenYellow
5700	Yellow - "Yellowish" (at times appears to be Lt gray or matel
5800	Light Orange or Yellow - Pink
6000	Carnation Pink
6300	Violet Red
6800	"Bluish" (appears violet red, Blue Green, looks $\underline{Blue}$
7200	Blue Green - Green
7700	"Yellowish"
8000	Orange
8200	Salmon
8500	Dull, Light Red Violet
8600	Violet
8700	Blue Violet
8900	Blue Blue
9200	Blue Green
9500	Dull Yellow Green
9700	Yellow - "Yellowish"
9900	Orange
10000	Carnation Pink



Nitride Thickness = (Oxide Thickness)(Oxide Index/Nitride Index) Eg. Yellow Nitride Thickness = (2000)(1.46/2.00) = 1460

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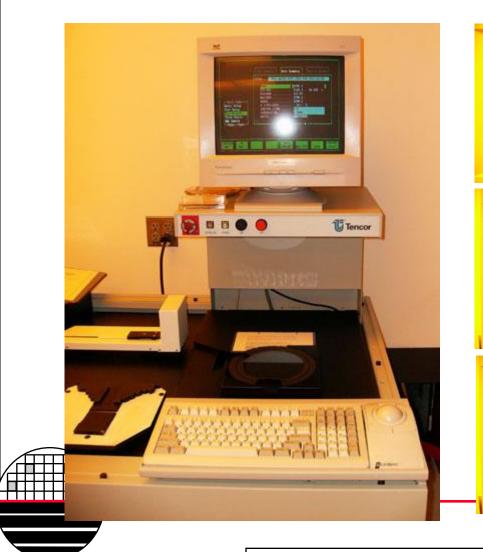
### NANOSPEC FILM THICKNESS MEASUREMENT TOOL

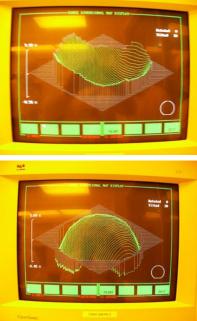


Rochester Institute of Technology Microelectronic Engineering Record: Color = Blue-Green Color Chart Thickness = ÅNanospec Thickness = Å

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### **TENCORE FT-300 SPECROMAP**





### Record:

Mean Std Deviation Min Max No of Points

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Page 13

Tilted 30

### *FT500*



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### **ELLIPSOMETER MEASUREMENTS**



Measure wafers C1 and C2

Pattern 20 is 1 point in center of wafer Pattern 22 is 5 points on 4" wafer Pattern 25 is 5 points on 6" wafer

Recipe 03 is oxide on silicon Recipe 07 is nitride on oxide on silicon Recipe 02 is used for one film and finds thickness and index of refraction

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### MEASURE C1 AND C2 ON SCA-2500

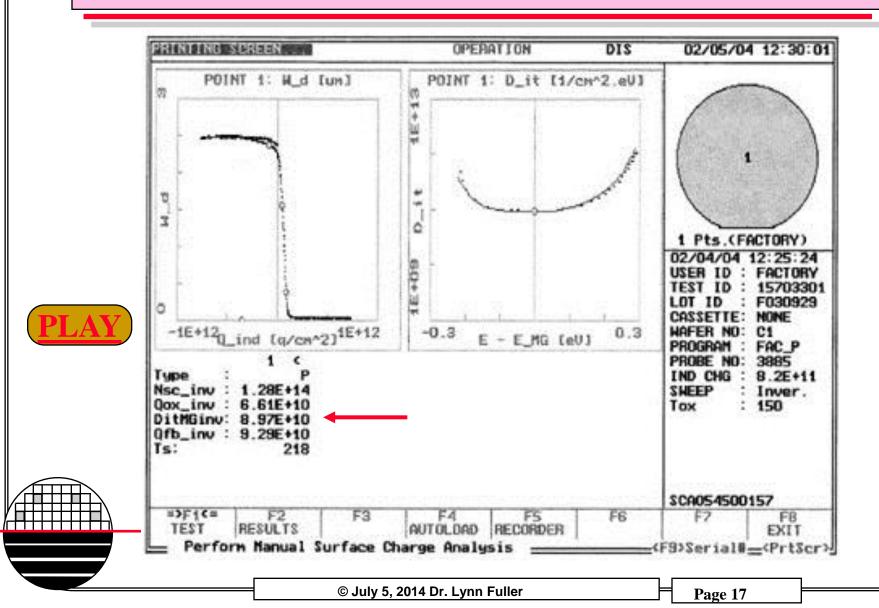
Login: FACTORY **Password: OPER** <F1> Operate **<F1> Test** Center the wafer on the stage Select (use arrow keys on the numeric pad (far right on the keyboard) space bar, page up, etc) **PROGRAM = FAC-P or FAC-N** LOT ID = F040909WAFER NO. = D1 TOX = 463 (from nanospec) <F12> start test and wait for measurement <**Print Screen> print results** <F8> exit and log off <ESC> can be used anytime, but wait for current test to be completed

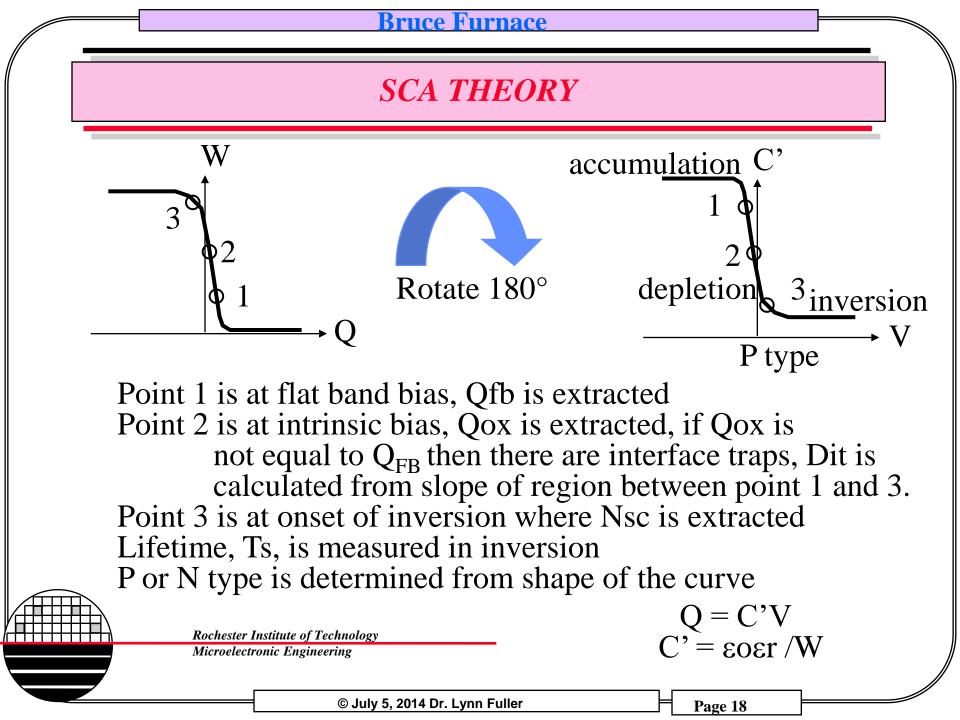


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#### SCA MEASUREMENT OF GATE OXIDE





## **RECALL RUN DATA**

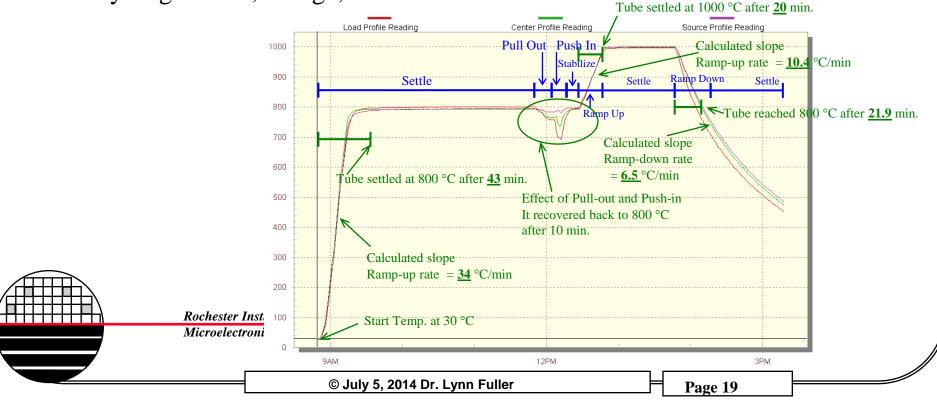
Click on the furnace tube of interest.

Click on the graph icon on the left end of the top banner.

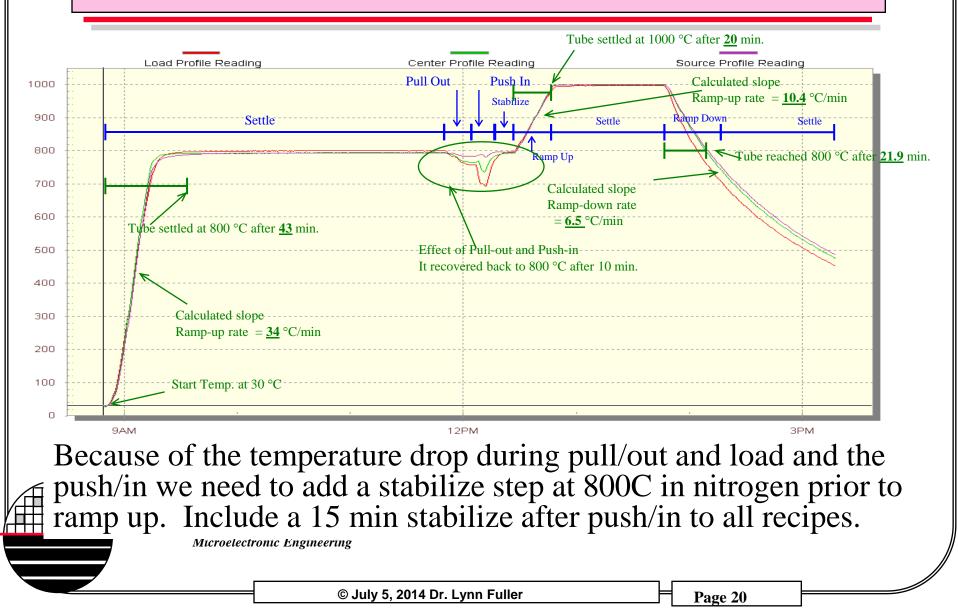
Select last month.

Select the furnace run of interest.

Select the items to be graphed. Example: center profile, red, add; nitrogen flow, blue, add; oxygen flow, green, add; hydrogen flow, orange, add.



### **STABILIZE AFTER PUSH**

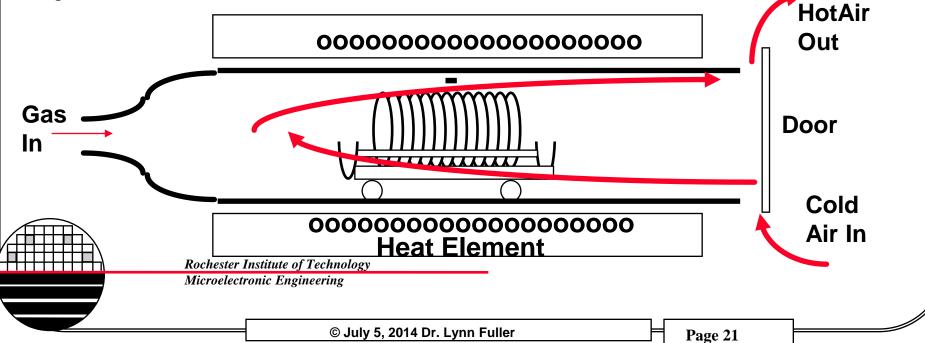


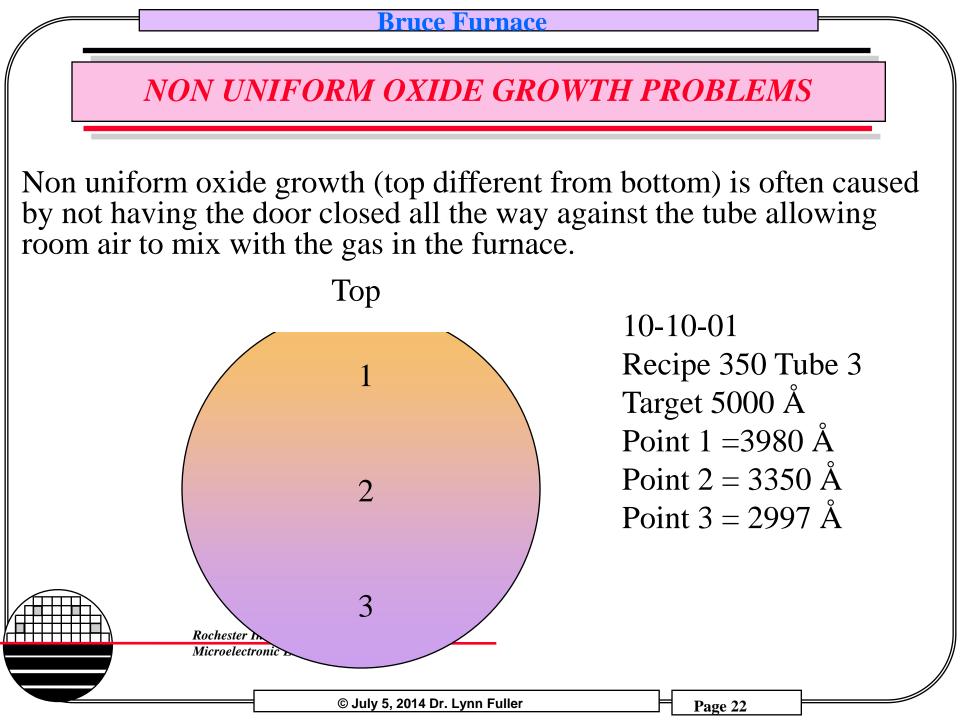
#### NON UNIFORM OXIDE GROWTH PROBLEMS

Non uniform oxide growth (top different from bottom) is often caused by not having the door closed all the way against the tube allowing room air to mix with the gas in the furnace. A similar effect is caused by having the gas flow rates too high or too low. The flow should slowly push a volume of air down the tube, without turbulence and without high velocity as it passes by the wafers. If the flow is too low then the door needs to be closed more accurately.

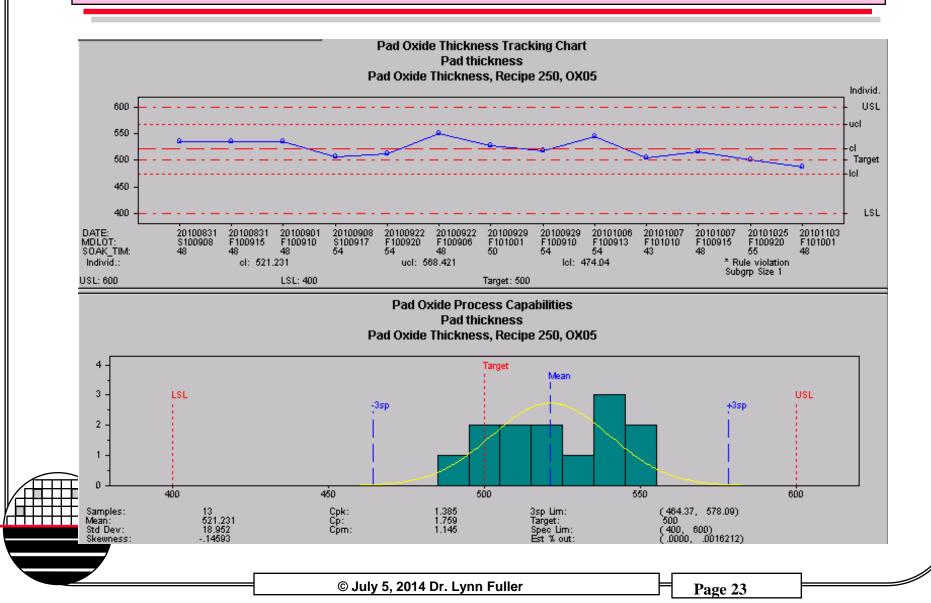
Use Total flow (lpm) = v (cm/s) x Area (cm2) x 60 (s/m) x 0.001 (l/cm3) and let v = 1.0 cm/s. For 20 cm diameter tube Total Flow= 18 lpm

The Bruce Furnace at RIT uses flows from 5 lpm to 15 lpm, These are all on the low side to reduce gas usage.

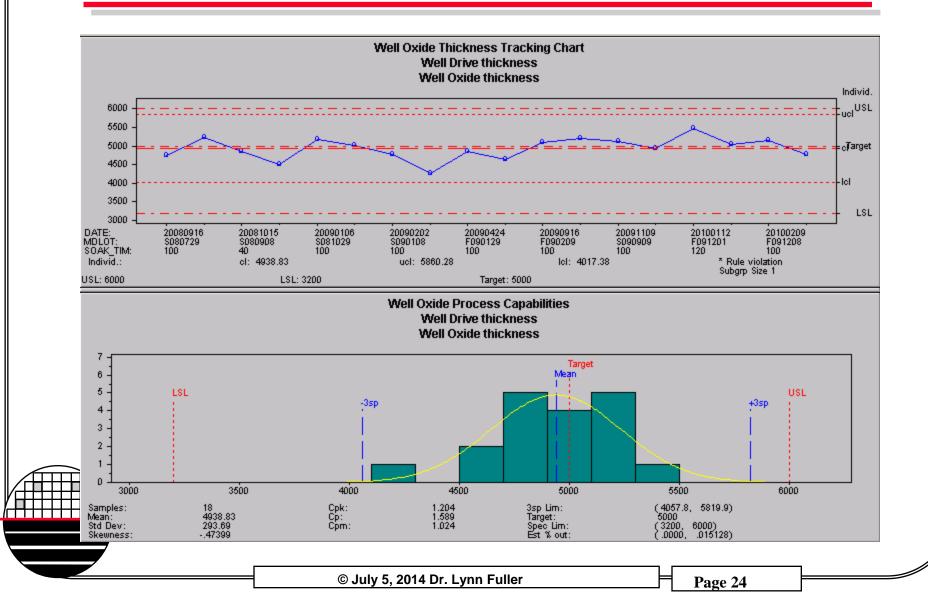




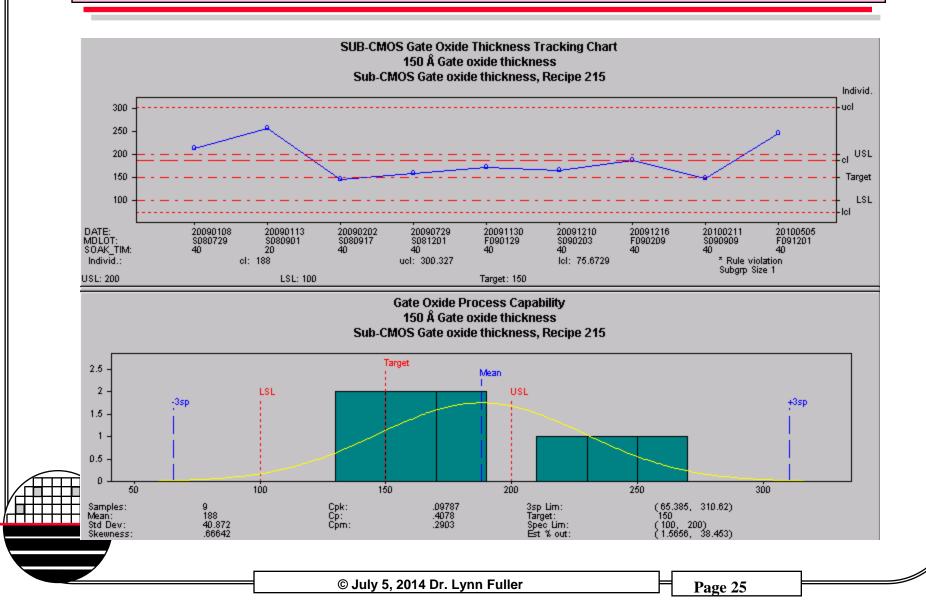
#### PAD OXIDE - SPC CHART



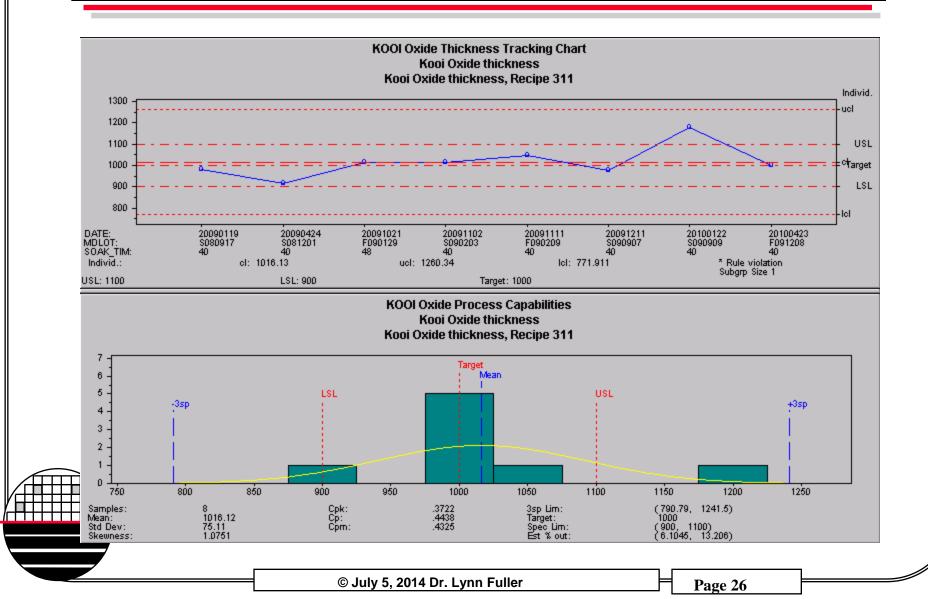
#### WELL OXIDE – SPC CHART



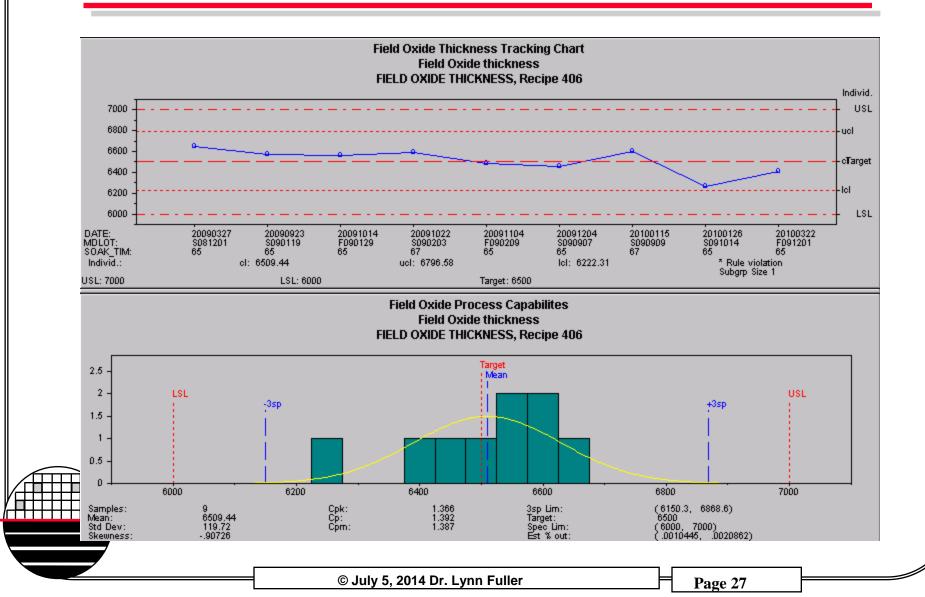
### GATE OXIDE – SPC CHART



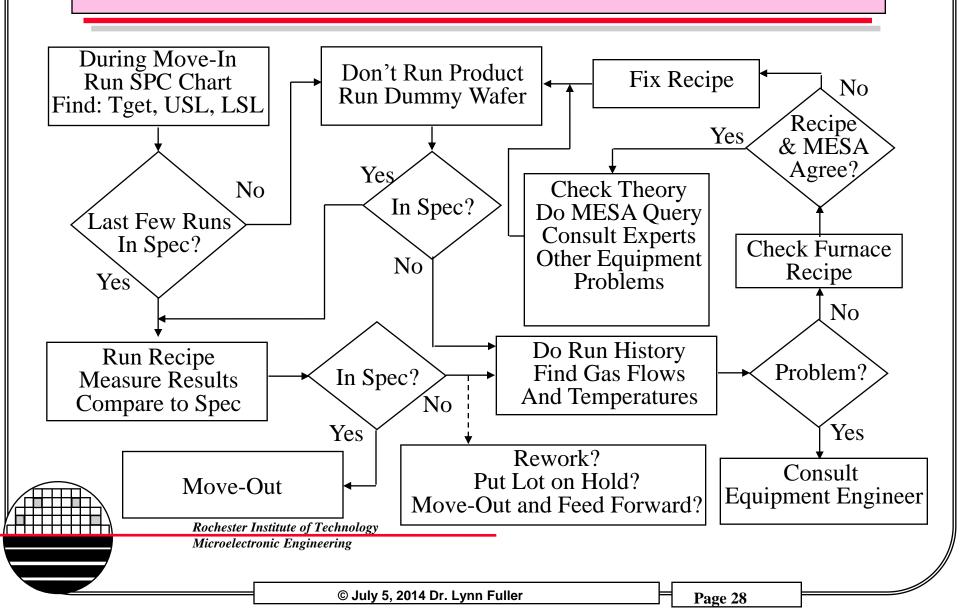
#### **KOOI OXIDE – SPC CHART**



### FIELD OXIDE – SPC CHART



### **OUT OF CONTROL ACTION PLAN**



#### BAKE OF SPIN-ON DOPANT 200 °C FOR 15 MIN.



Use quartz boat from furnace tube you plan to use.

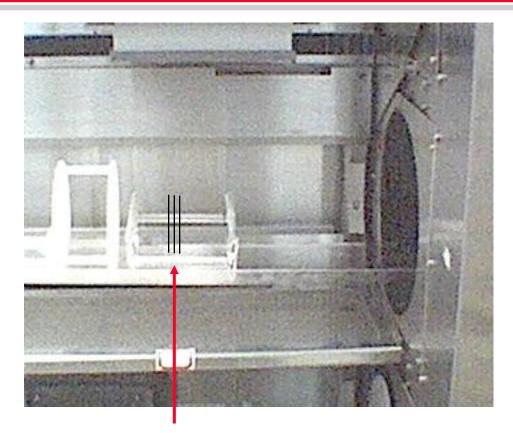
Use holder as shown because the boat will be hot.

Do not heat wafers with photoresist on them above 150 °C

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### **POSITION OF WAFERS ON PADDLE**



Load wafers here, when paddle is fully out. Do not use dummy filler wafers... the improved uniformity is negligible.

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## **CREATING NEW RECIPES**

Log In as engineer Find a similar recipe Edit > Copy > new recipe name

Pick a number that has not been used Make changes

save

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LIST OF RECIPES FOR BRUCE FURNACE

- 10 Lfull Sub CMOS Well, 1100 °C, 600 min, N2
- 11 Lfull Adv CMOS Well, 1100 °C, 360 min, N2
- 15 Lfull Well-Oxide, 1100 °C, 330 min, N2 + 25 min wet Oxide
- 16 Lfull TEOS Densification, 1hr. 1000°C, N2
- 99 Lfull Sinter, 400°C, 30min, N2/H2
- 101 Lfull Sinter, 450 °C, 30min, N2/H2
- 105 Lfull 1000 °C Anneal, 100 min, N2 only
- 106 Lfull Anneal sub-micron CMOS process, 900 °C, 30 min., N2
- 110 Lfull PMOS D/S Diffusion and Wet Ox, N2 then Wet O2
- 111 Lfull P+ Doping + Wet O2
- 115 Lfull N+ Doping + Wet O2
- 119 Lfull N+ Doping Thick Poly
- 120 Lfull N+ Poly Doping from Spin-on Source, 1000 °C, 15 min, N2 144 Lfull 1000°C Source/Drain Anneal

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LIST OF RECIPES FOR BRUCE FURNACE

162 Lfull Well Drive SMFL-CMOS 25hr, 1100°C, N2 163 Lfull SMFL-CMOS Field Oxide, 6500Å, 950°C, Wet Oxide 175 Lfull Poly ReOxide 850°C, Wet Oxide, 15 min. 180 Lfull Well Drive P-well CMOS, 6 hrs O2, 30 hrs N2, 1100 °C 210 Lfull 100Å Gate Oxide 213 Lfull 100Å Gate Oxide with N2O 215 Lfull 150Å Gate Oxide, 900 °C, 50 min, Dry O2 225 Lfull 250Å Gate Oxide 250 Lfull 500Å Dry Oxide, 1000 °C, 56 min., soak, Gate/Pad Ox 252 Lfull Dry Oxide Var Time, 1000 °C Set your own soak time 270 Lfull 700Å Dry Oxide, 1Hr. 24min. 1000 °C soak 280 Lfull D/S Implant Anneal, 1000 °C, 20 min N2 +10 min Wet O2 284 Lfull D/S Anneal, 1000 C, 25 min. N2 310 Lfull 1,000Å Dry Oxide, 2Hr. 18min. 1000 °C soak 311 Lfull 1,000Å Kooi/Sacrificial Oxide, 900 °C, Wet O2, 40 min.

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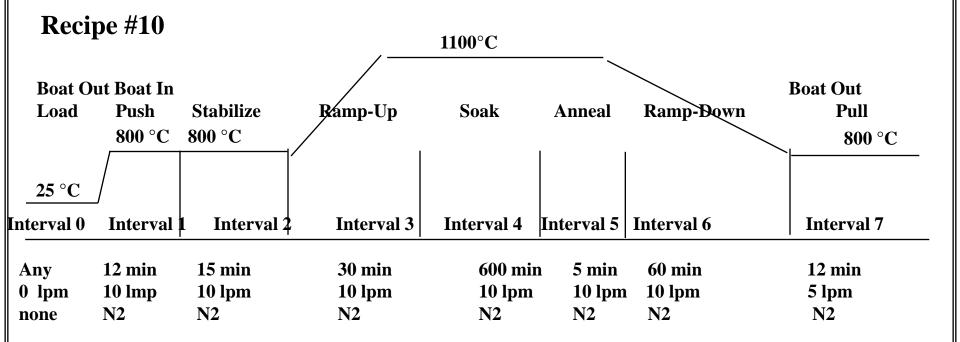
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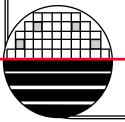
#### LIST OF RECIPES FOR BRUCE FURNACE

330 Lfull Wet 3,000 Å Wet Oxide, 1000 °C, 50 min. soak 336 Lfull Wet 3,650 Å Wet Oxide, 1000 °C, 55 min. soak 341 Lfull Wet 4,000Å Wet Oxide, 1100 °C, 20 min. soak 350 Lfull Wet 5,000Å Wet Oxide, 1000 °C, 100 min. soak 353 Short Course 5000Å, 1100 °C, 45 min, Wet Ox 354 Short Course PreDep, 1050 °C,  $5 \min N2 + 5 \min Wet Ox$ 355 Short Course Gate Ox, 1100 °C, 17min, Dry O2 356 Short Course Sinter, 357 Short Course 8000Å, 1100 °C, 95 min, Wet Ox 352 Lfull Wet Ox Var Time, 1100 °C, Set your own soak time 406 Lfull 6,500Å Wet Oxide, Field Ox, 1100 °C, 65 min. soak 410 Lfull 10,000Å Wet Oxide, Field Ox, 1100 °C, 210 min. soak 430 Lfull 30,000Å Wet Oxide, Field Ox, 1100 °C, 15 Hr. soak 440 Lfull 40,000Å Wet Oxide, Field Ox, 1100 °C, 35 Hr. soak 463 SMFL TransLC Tube Clean, Tube 4 474 Lfull SMFL CMOS 310Å Gate Oxide, N2/O2, 1000C,15 min.

**BRUCE FURNACE RECIPE 10 SUB-CMOS WELL DRIVE** 



At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.



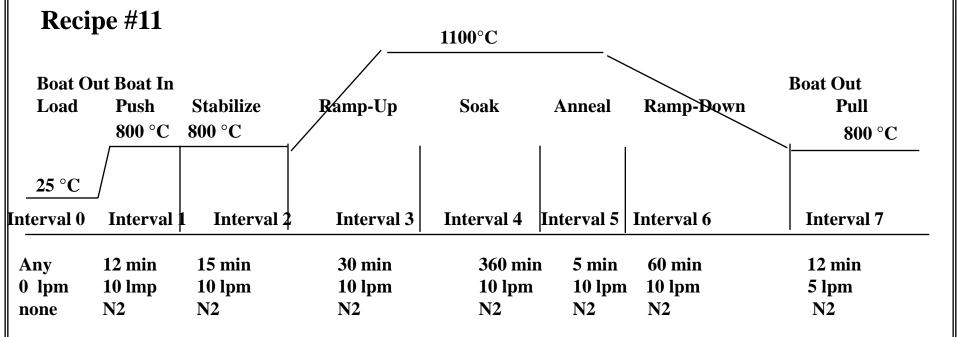
Sub-CMOS Well Drive, No Oxide Growth, Tube 1

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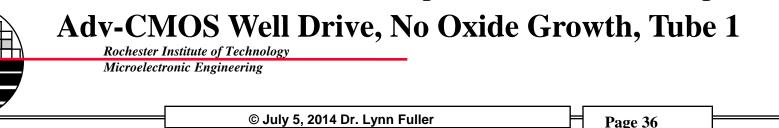
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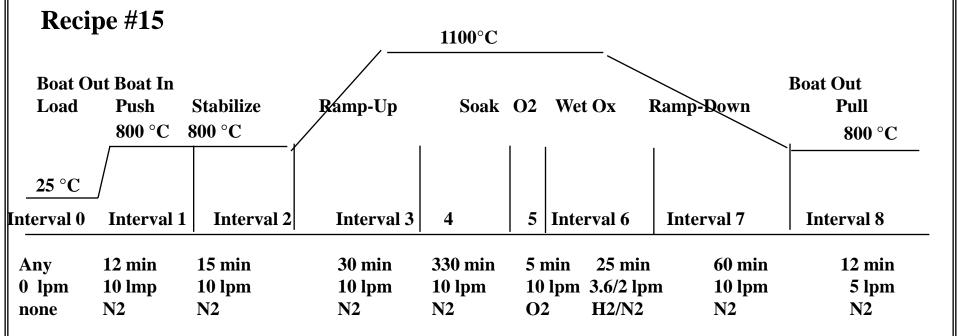
### **BRUCE FURNACE RECIPE 11 ADV-CMOS WELL DRIVE**



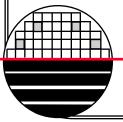
At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.







At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

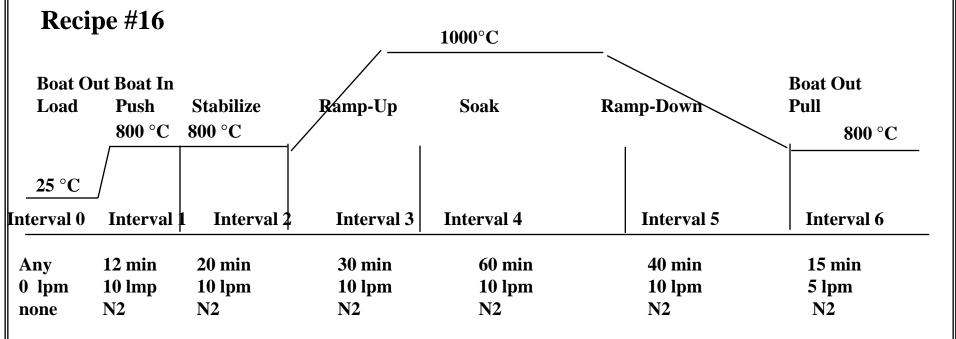


CMOS Well Drive, 3000Å Wet Oxide Growth, Tube 1

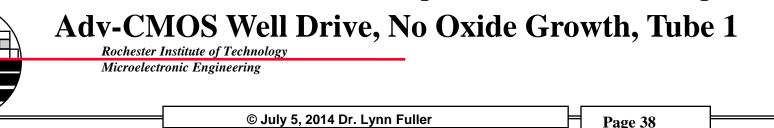
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### **BRUCE FURNACE RECIPE 16 ADV-CMOS WELL DRIVE**



At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.





**BRUCE FURNACE RECIPE 99 SINTER** 

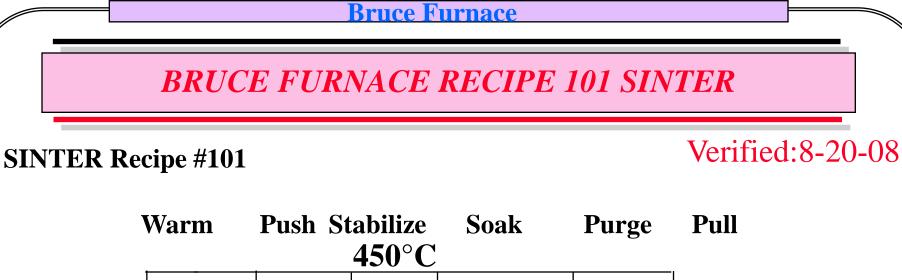
**SINTER Recipe #99** 

	Warm	Push	Stabilize 400°C	Soak	Anneal	Pull
<u>25 °C</u>						25 °C
Interval 0	1	2	3	4	5	6
Any 0 lm None	p 10	30 10 N2	15 10 N2	15 5 N2/H2	5 10 N2	15 min 5 lpm N2

At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

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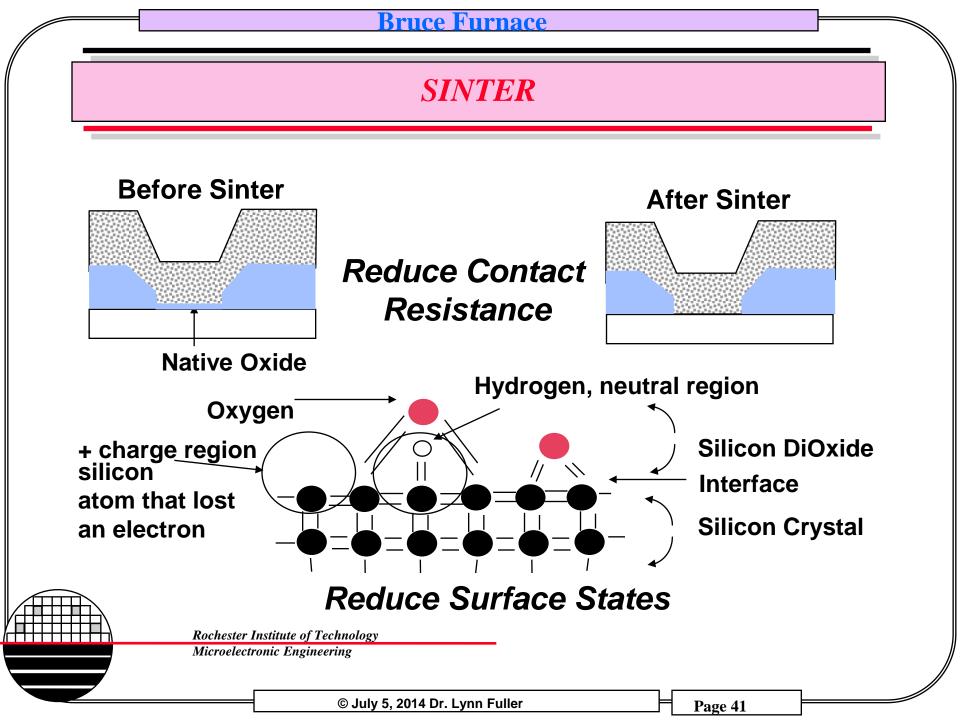
Sinter, Tube 2



W T	arm	Push S	Stabilize 450°C	Soak	Purge	<b>Pull</b>
<u>25 °C</u>						25 °C
Interval 0	1	2	3	4	5	6
Any` 0 lmp None	60 10 N2	30 10 N2	15 10 N2/H2	15 5 N2/H2	5 10 N2	15 min 5 lpm N2

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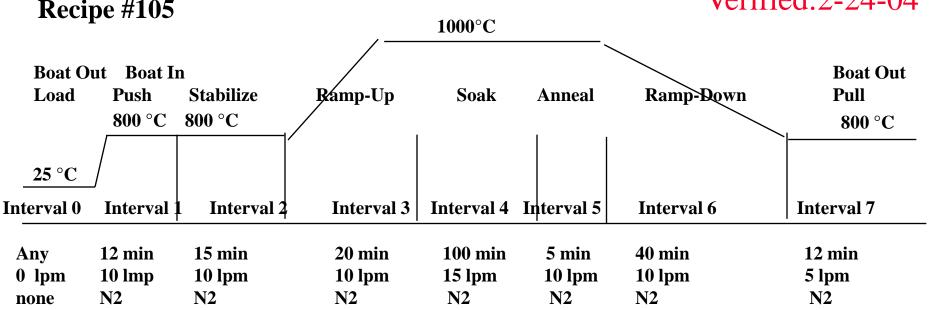
Sinter, Tube 2













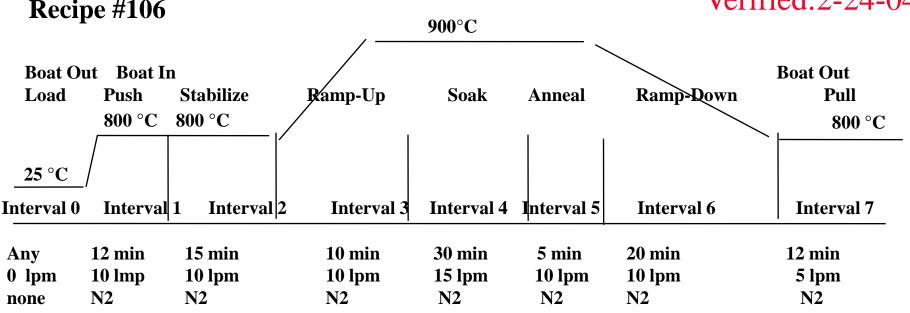
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### BRUCE FURNACE RECIPE 106 – 900°C ANNEAL

Verified:2-24-04

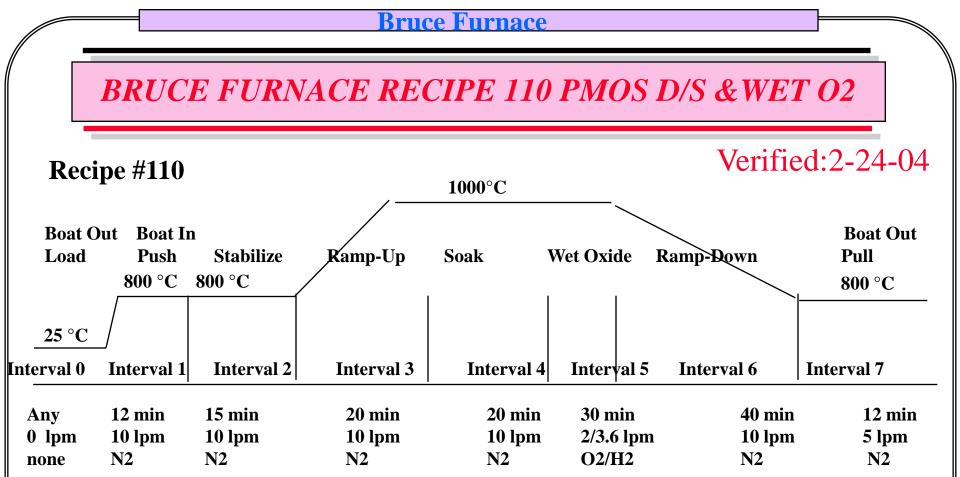


At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

### 900°C Anneal, No Oxide Growth

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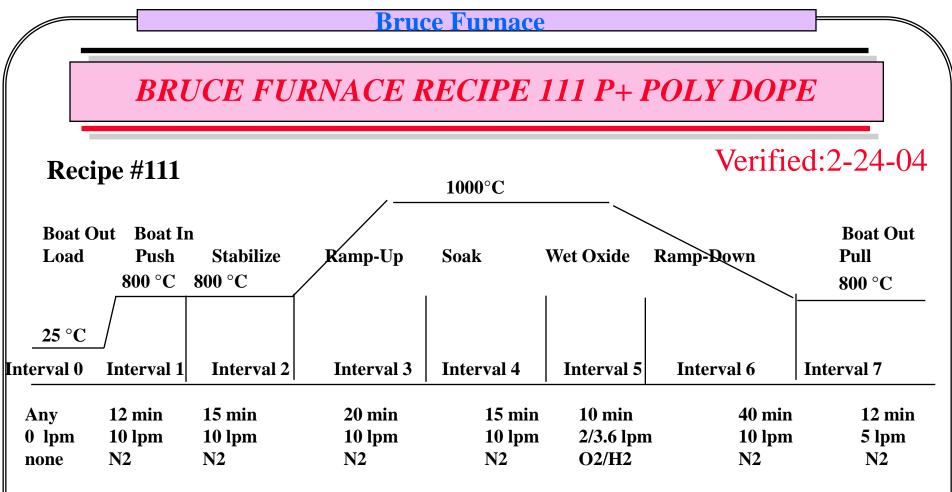
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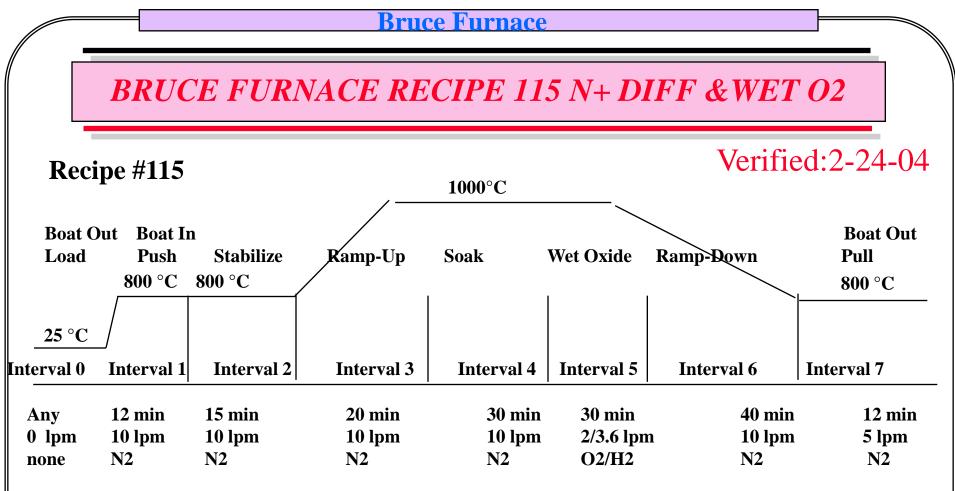
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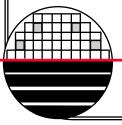




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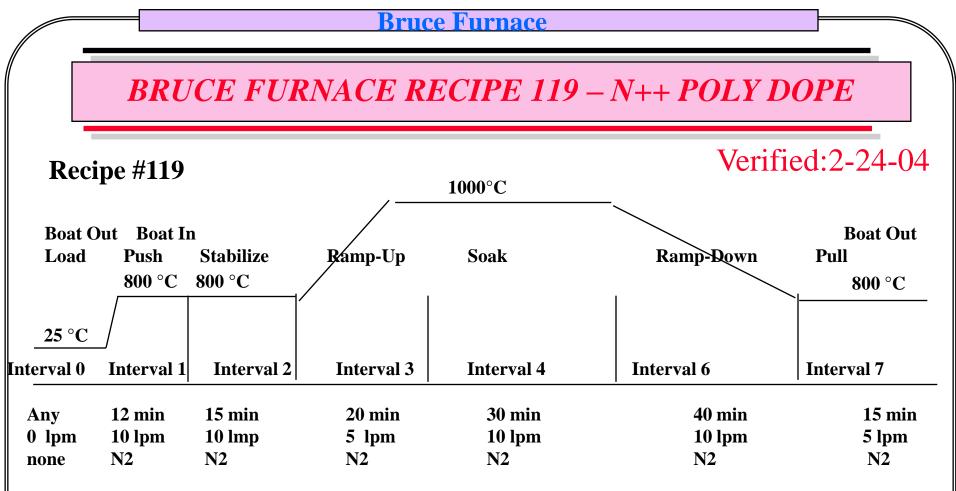




N+ Diffusion plus Wet Oxide Growth, Target 2854 Å

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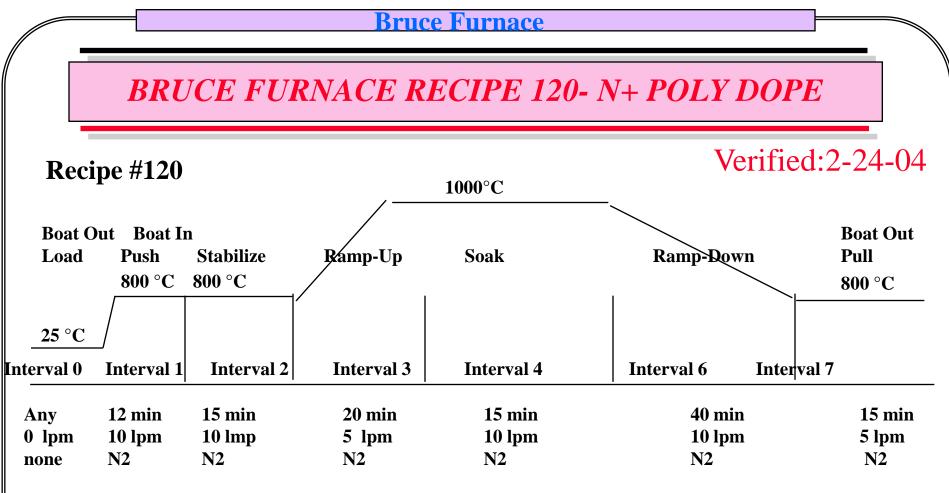
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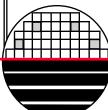


N+ Poly Doping, Thick Poly,  $> 1 \mu m$ , No Oxide Growth

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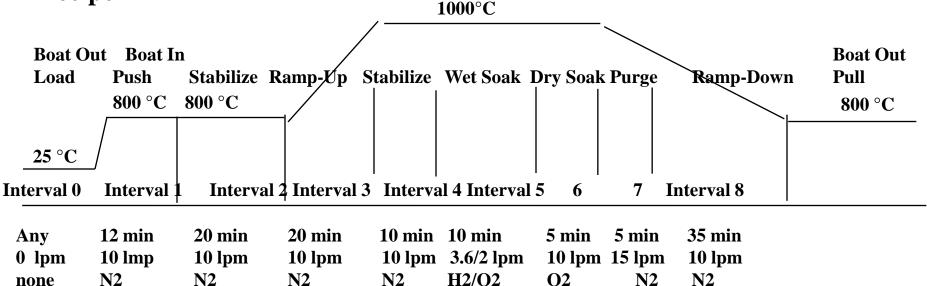


N+ Poly Doping, Thin Poly, < 1  $\mu$ m, No Oxide Growth

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BRUCE FURNACE RECIPE 144 – 1000°C S/D ANNEAL





At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

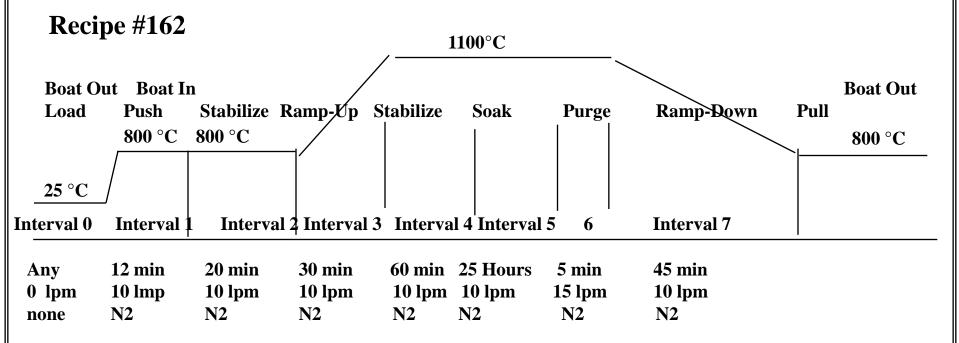
1000°C Anneal, With Oxide Growth

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BRUCE FURNACE RECIPE 162 – 1100°C 25HR WELL DRIVE

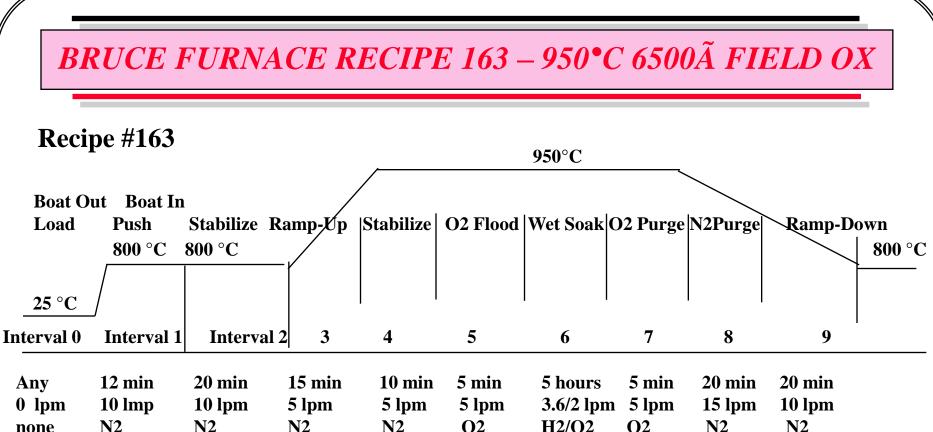


At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

# 1100°C Well Drive, No Oxide Growth

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At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

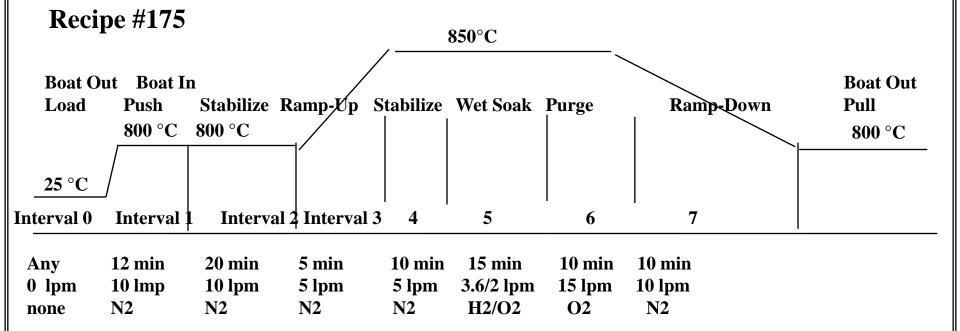
950°C Wet Oxide Growth, Target 6500Å

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850°C Poly Reoxide	_
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Verified:2-24-04

NUU	рс #100			1100°C			
Boat C Load	out Boat Ir Push 800 °C	1 Stabilize 800 °C	Ramp-Up	Soak	Anneal	Ramp-Dow	Boat Out n Pull 800 °C
<u>25 °C</u> Interval 0	Interval 1	Interval 2	Interval 3	Interval 4	Interval 5	Interval 6	Interval 7
Any 0 lpm none	12 min 10 lpm N2	15 min 10 lmp N2	30 min 5 lpm O2	6 hr 10 lpm O2	30 hr 15 lpm N2	60 min 10 lpm N2	15 min 5 lpm N2

### **P-well CMOS Drive and Oxide Growth**

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Recipe #180

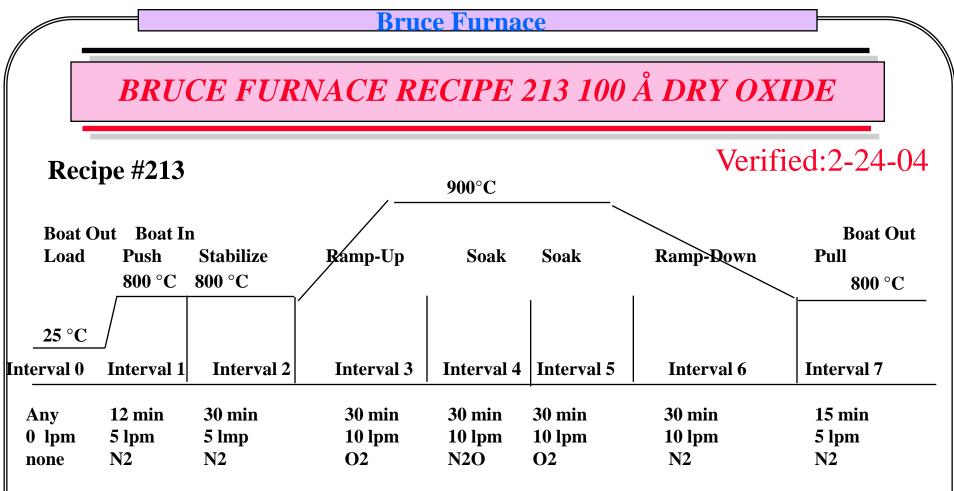
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				Bruce F	urnace					
	BRU	CE FU	RNACE	E RECI	PE 210	- TUN	NEL O	XIDE		
Reci	pe #210				950°C					
Boat O Load	Push	n Ramp-Up	Soak O2	Anneal	Soak O2	Anneal	Soak O2	Anneal	$\mathbf{i}$	t Out Pull
25 °C	800 °C									300 °C
Interval 0	1	2	3	4	5	6	7	8	9	10
Any 0 lpm none	12 min 10 lpm N2	30 min 10 lmp N2	15 min 10 lpm O2	60min 5 lpm N2	10 min 10 lpm O2	20 min 5 lpm N2	10 min 10 lpm O2	30 min 5 lpm N2	30min 10 lpm N2	

# **Tunnel Oxide for EEPROM, Target 100 Å**

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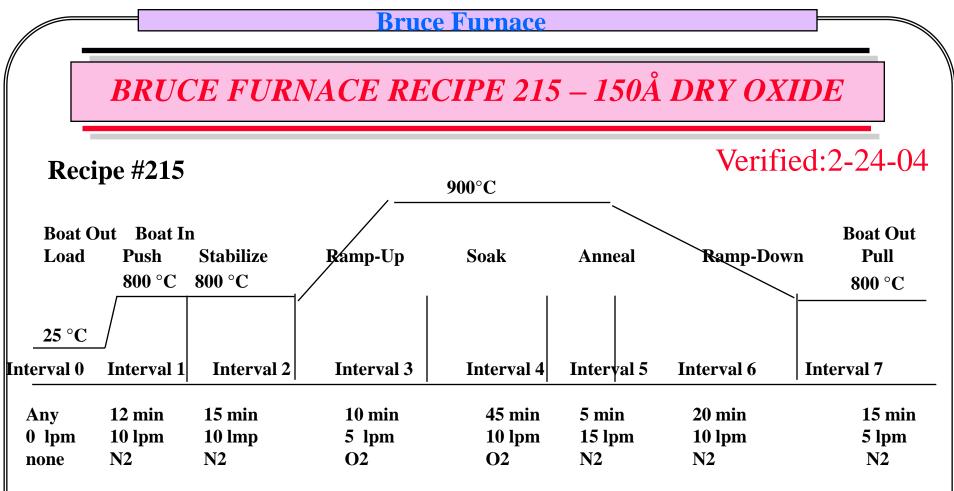
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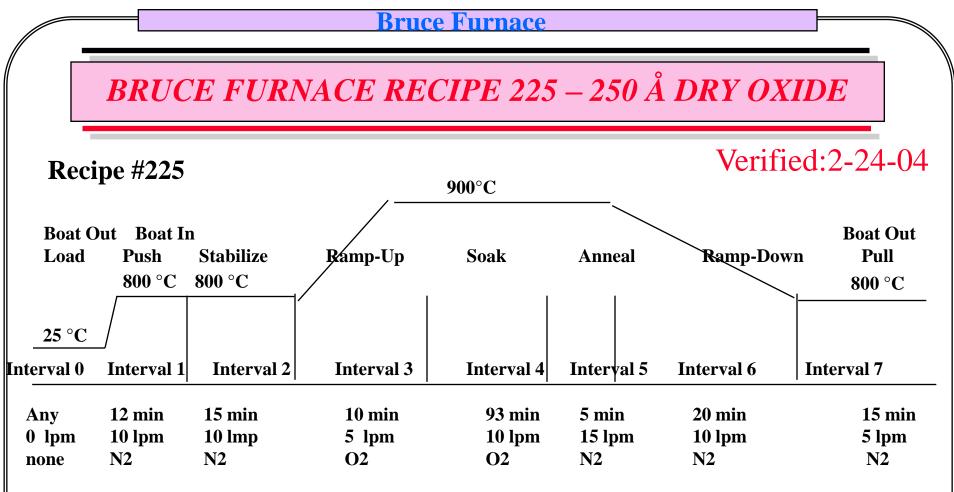
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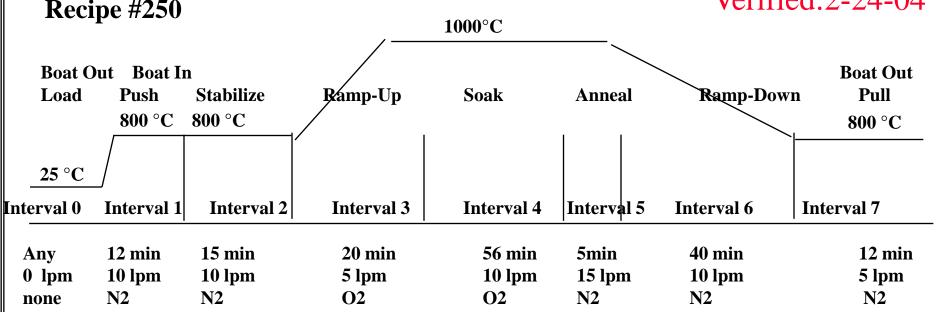
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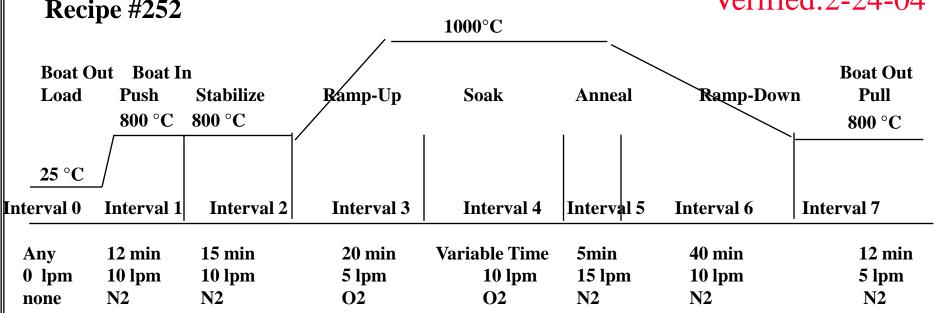
## Dry Oxide Growth, Target 500 Å

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Verified:2-24-04

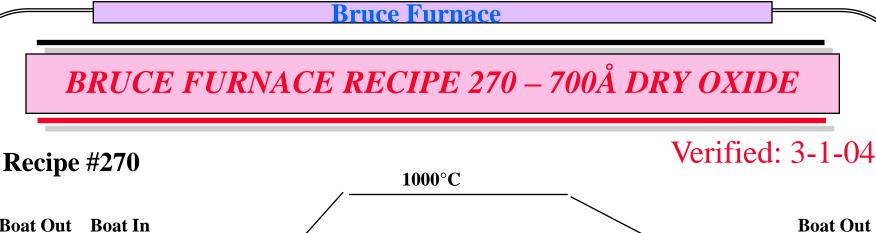


At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

### Dry Oxide Growth, Variable Target

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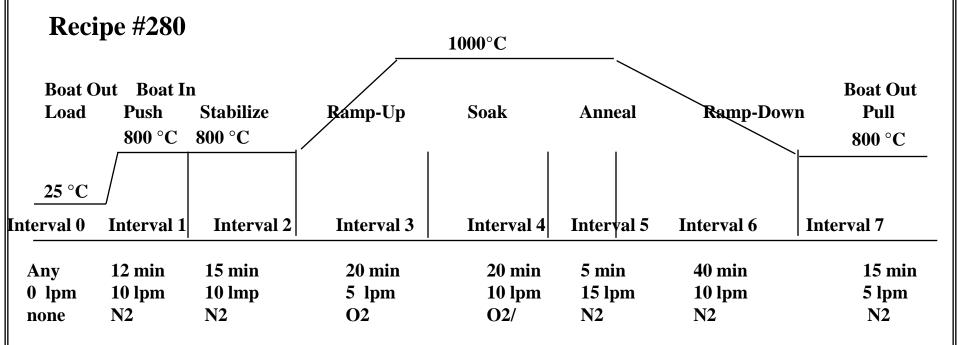
Boat O Load	out Boat In Push 800 °C	n Stabilize 800 °C	Ramp-Up	Soak	Anneal	Ramp-Dowr	Boat Out n Pull 800 °C
25 °C Interval 0	Interval 1	Interval 2	Interval 3	Interval 4	Interval 5	Interval 6	Interval 7
Any 0 lpm none	12 min 10 lpm N2	15 min 10 lmp N2	20 min 5 lpm O2	93 min 10 lpm O2/	5 min 15 lpm N2	40 min 10 lpm N2	15 min 5 lpm N2

# Dry Oxide Growth, Target 700 Å

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### **BRUCE FURNACE RECIPE 280 – Sub-CMOS ANNEAL**



At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

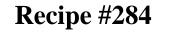
## DS Implant Anneal, Oxide Growth

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1000°C



				1000 C			
Boat C Load	out Boat Ir Push 800 °C	1 Stabilize 800 °C	Ramp-Up	Soak	Anneal	Ramp-Down	Boat Out Pull 800 °C
<u>25 °C</u> Interval 0	 Interval 1	Interval 2	Interval 3	Interval 4	Interval 5	Interval 6	Interval 7
Any 0 lpm none	12 min 10 lpm N2	15 min 10 lmp N2	20 min 5 lpm N2	20 min 10 lpm N2	5 min 15 lpm N2	40 min 10 lpm N2	15 min 5 lpm N2

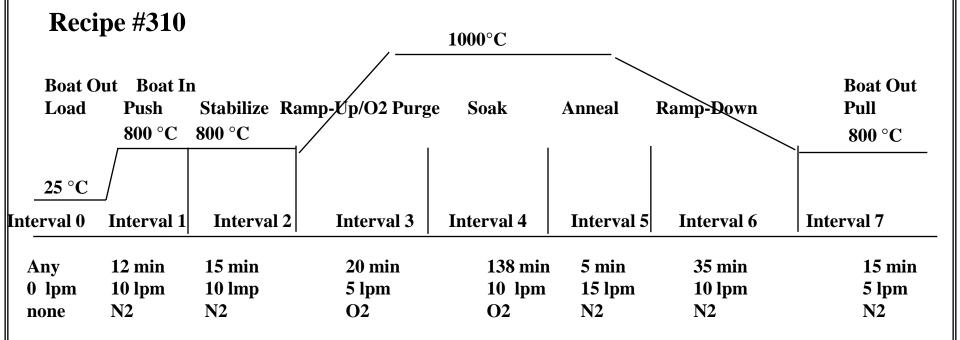
At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.



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BRUCE FURNACE RECIPE 310 – DRY OXIDE 1,000Å



At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

# Dry Oxide Growth, Target 1000 Å

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BRUCE FURNACE RECIPE 311 – WET OXIDE 1,000Å

### Recipe #311

	-			9	00°C			
Boat O Load	out Boat Ir Push 800 °C	n Stabilize Ra 800 °C	amp-10p/O2 ]	Purge	Soak	Anneal	Ramp-Down	Boat Out Pull 800 °C
25 °C	Interval 1	Interval 2	Interval 3	4	Interval 5	Interval 6	Interval 7	Interval 8
Any 0 lpm none	12 min 10 lpm N2	15 min 10 lmp N2	10 min 5 lpm O2	5 min 10 lpm O2	40 min 3.6/2.0 l O2/H2	5 min pm 15 lpm N2	15 min 10 lpm N2	15 min 5 lpm N2

At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

# Wet Oxide Growth, Target 1000 Å, Kooi

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BRUCE FURNACE RECIPE 330 – WET OXIDE 3,000Å

Reci	pe #330	Lfull 300	0 A Wet	Ox 1000	0°C			
Boat O	ut Boat Iı	n						<b>Boat Out</b>
Load	Push	Stabilize	Ramp-Up	Flood	Soak	Anneal	Ramp-Down	Pull
25 °C	800 °C	800 °C						800 °C
Interval 0	Interval 1	Interval 2	Interval 3	Interval 4	Interval 5	Interval 6	<b>Interval 7</b>	Interval 8
Any 0 lpm none	12 min 10 lpm N2	15 min 10 lpm N2	20 min 5 lpm N2	5 min 10 lpm O2	50 min 3.6/2.0 lpm O2/H2	5 min 15 lpm N2	40 min 10 lpm N2	12 min 5 lpm N2

At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

Wet Oxide Growth, Target 3000 Å

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BRUCE FURNACE RECIPE 336 – WET OXIDE 3,650Å

Reci	pe #336	Lfull 365	0 A Wet	Ox 100	0°C			
Boat O		-						Boat Out
Load	Push 800 °C	Stabilize 800 °C	Ramp-Up	Flood	Soak	Anneal	Ramp-Down	Pull 800 °C
25 °C			/					
terval 0	Interval 1	Interval 2	Interval 3	Interval 4	Interval 5	Interval 6	Interval 7	Interval 8
Any	12 min	15 min	20 min	5 min	55 min	5 min	<b>40 min</b>	12 min
0 lpm	10 lpm	10 lpm	5 lpm	10 lpm	3.6/2.0 lpm	n 15 lpm	<b>10 lpm</b>	5 lpm
none	N2	N2	N2	02	O2/H2	N2	N2	N2

At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

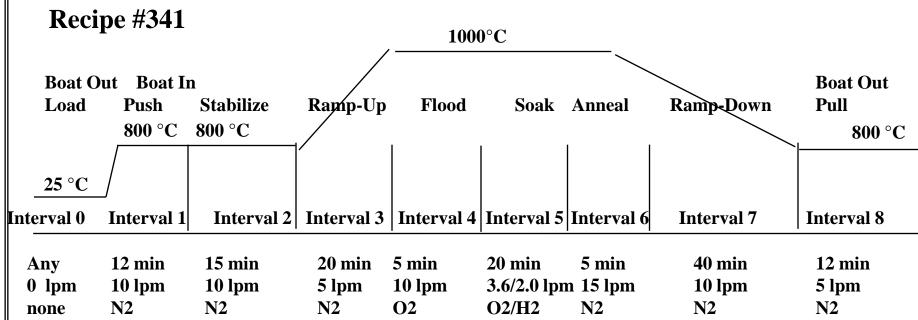
Wet Oxide Growth, Target 3650 Å

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BRUCE FURNACE RECIPE 341 – WET OXIDE 4,000Å



At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.

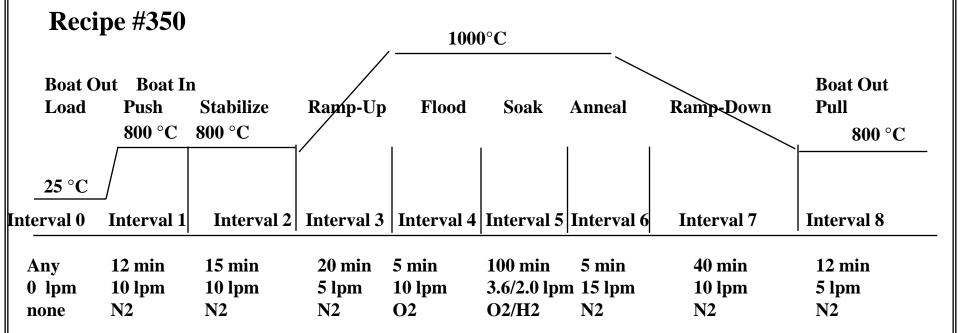


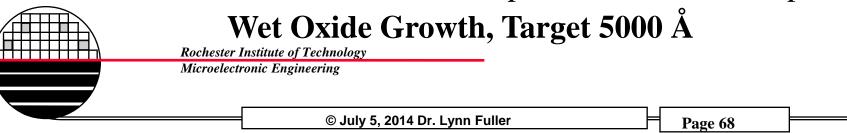
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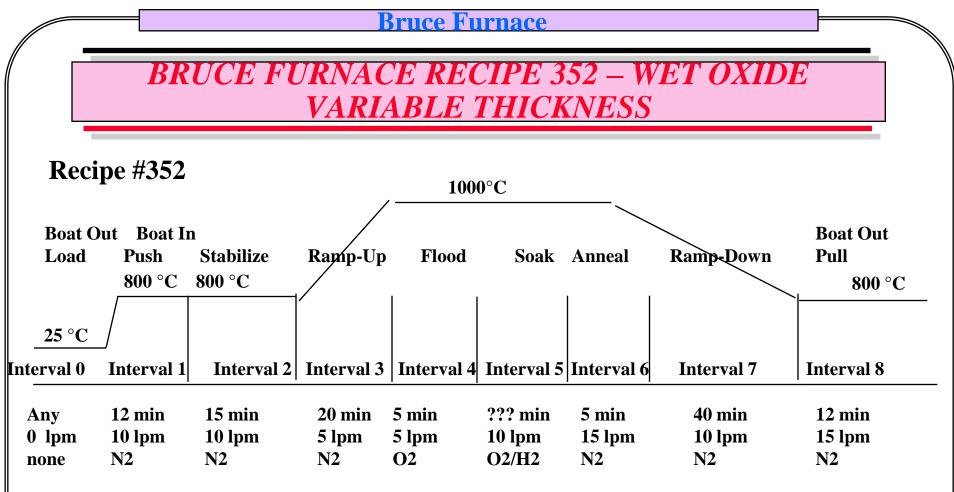
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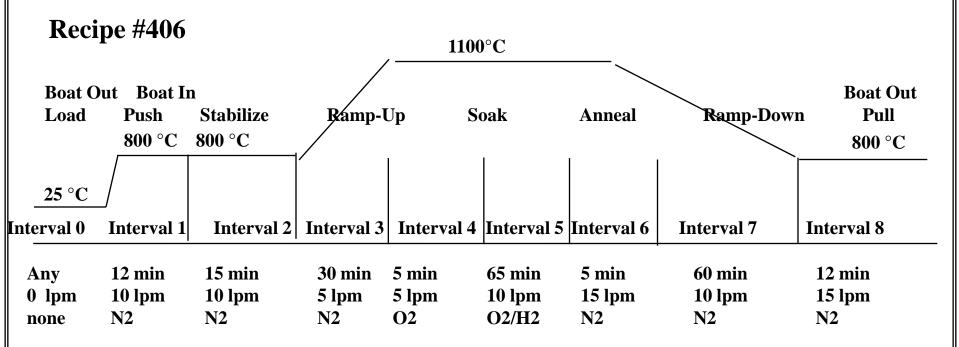








BRUCE FURNACE RECIPE 406 – WET OXIDE 6,500Å



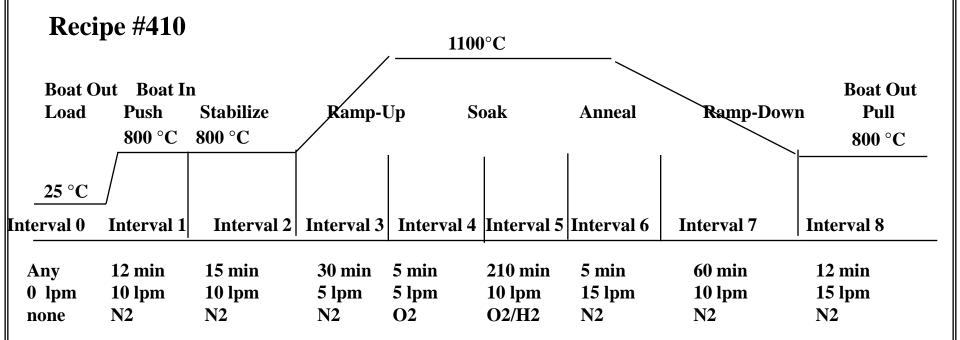
At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.



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BRUCE FURNACE RECIPE 410 – WET OXIDE 12,000Å



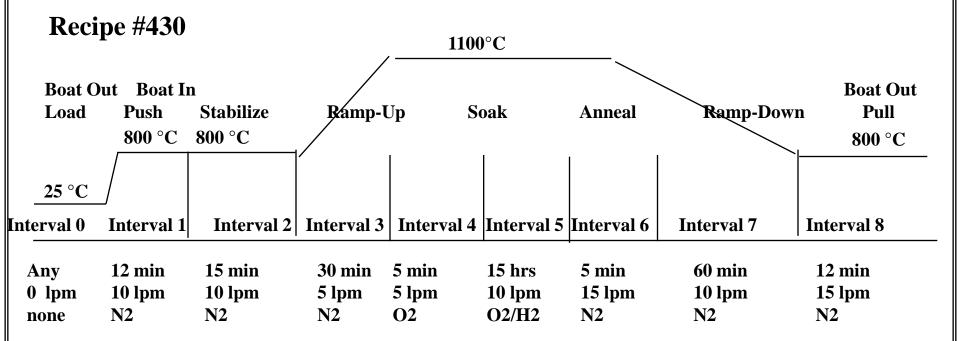
At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.



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BRUCE FURNACE RECIPE 430 – WET OXIDE 30,000Å



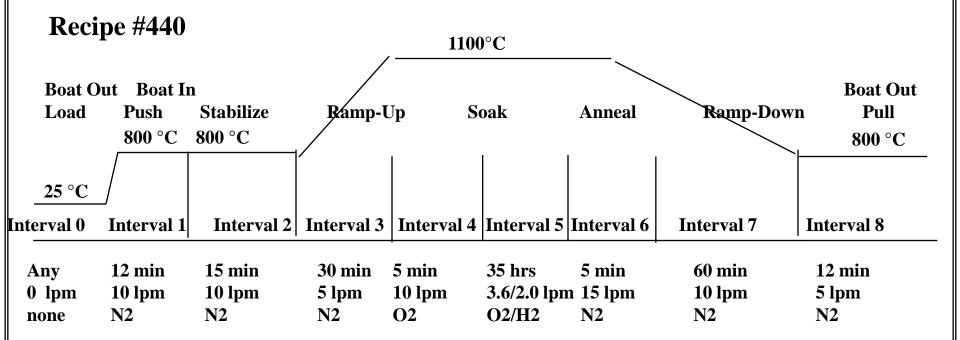
At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.



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BRUCE FURNACE RECIPE 440 – WET OXIDE 40,000Å

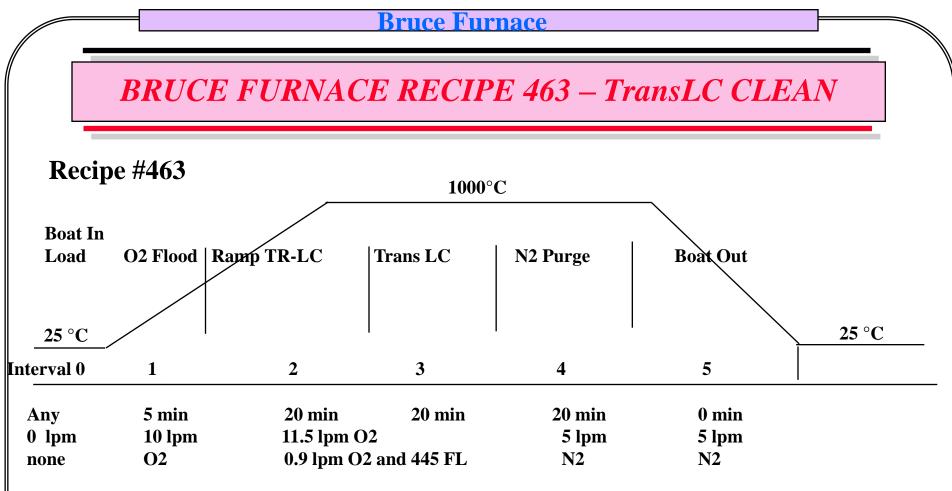


At the end of a run the furnace returns to Interval 0 which is set for boat out, 25 °C and no gas flow. The furnace waits in that state until someone aborts the current recipe or loads a new recipe.



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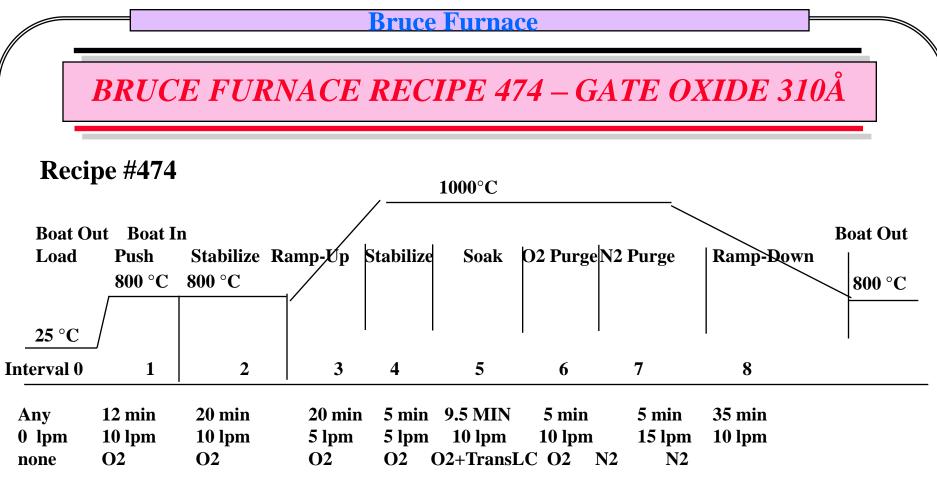
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1000°C 310Å Gate Oxide Growth

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### **REFERENCES**

1. Sdfklj

2. slfj

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